

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	IS&R	L1	0	("component\$ and fiduci\$").PN.	USPAT; EPO; JPO; Derwen t; IBM TDB	2001/02/11 17:04
2	IS&R	L7	0	("component\$ and fiducial").PN.	USPAT; EPO; JPO; Derwen t; IBM TDB	2001/02/11 17:05
3	BRS	L13	1344	component\$ and fiducial	USPAT	2001/02/11 17:08
4	BRS	L14	269	component\$ same fiducial	USPAT	2001/02/11 17:09

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1			0
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3		Truncation Overflow. Return string from Server is: 5'0'0'COM	1
4		Truncation Overflow. Return string from Server is: 5'0'0'COM	1

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S PN = US 5894218  
S1 1 PN = US 5894218

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UNITED STATES OF AMERICA (US)

Patent (No,Kind,Date): US 5894218 A 19990413  
METHOD AND APPARATUS FOR AUTOMATICALLY POSITIONING ELECTRONIC DIE  
WITHIN COMPONENT PACKAGES (English)

Patent Assignee: MICRON TECHNOLOGY INC (US)

Author (Inventor): FARNWORTH WARREN M (US); WOOD ALAN G (US);  
JACOBSON JOHN O (US); HEMBREE DAVID R (US); WARK JAMES M (US);  
FOLARON JENNIFER L (US); FOLARON ROBERT J (US); NELSON JAY C (US);  
WARREN LELAN D (US)

Priority (No,Kind,Date): US 693398 A 19960807; US 228809 B2  
19940418

Applic (No,Kind,Date): US 693398 A 19960807

National Class: \* 324158100; 324754000

IPC: \* G01R-031/02

Derwent WPI Acc No: \* G 95-373964; G 99-263246; G 99-539638; G  
01-089980; G 99-263246

Language of Document: English

Patent (No,Kind,Date): US 5955877 A 19990921  
METHOD AND APPARATUS FOR AUTOMATICALLY POSITIONING ELECTRONIC DIE  
WITHIN COMPONENT PACKAGES (English)

Patent Assignee: MICRON TECHNOLOGY INC (US)

Author (Inventor): FARNWORTH WARREN M (US); WOOD ALAN G (US);  
JACOBSON JOHN O (US); HEMBREE DAVID R (US); WARK JAMES M (US);  
FOLARON JENNIFER L (US); FOLARON ROBERT J (US); NELSON JAY C (US);  
WARREN LELAN D (US)

Priority (No,Kind,Date): US 170844 A 19981013; US 693398 A3  
19960807; US 228809 B2 19940418

Applic (No,Kind,Date): US 170844 A 19981013

Addnl Info: 5894218 Patented

National Class: \* 324158100; 324765000

IPC: \* G01R-031/26

Derwent WPI Acc No: \* G 95-373964; G 99-263246; G 99-539638; G  
01-089980; G 99-539638

Language of Document: English

Patent (No,Kind,Date): US 6064194 A 20000516

METHOD AND APPARATUS FOR AUTOMATICALLY POSITIONING ELECTRONIC DIE  
WITHIN COMPONENT PACKAGES (English)

Patent Assignee: MICRON TECHNOLOGY INC (US)

Author (Inventor): FARNWORTH WARREN M (US); FOLARON JENNIFER L (US);  
FOLARON ROBERT J (US); HEMBREE DAVID R (US); JACOBSON JOHN O (US);  
NELSON JAY C (US); WARREN LELAND (US)

Priority (No,Kind,Date): US 767700 A 19961217; US 228809 B1  
19940418

Applic (No,Kind,Date): US 767700 A 19961217

National Class: \* 324158100; 324765000

IPC: \* G01R-031/02

Derwent WPI Acc No: \* G 95-373964; G 99-263246; G 99-539638; G  
01-089980

Language of Document: English

Patent (No,Kind,Date): US 6150828 A 20001121

METHOD AND APPARATUS FOR AUTOMATICALLY POSITIONING ELECTRONIC DIE WITH  
COMPONENT PACKAGES (English)

Patent Assignee: MICRON TECHNOLOGY INC (US)

Author (Inventor): FARNWORTH WARREN M (US); WOOD ALAN G (US);  
JACOBSON JOHN O (US); HEMBREE DAVID R (US); WARK JAMES M (US);  
FOLARON JENNIFER L (US); FOLARON ROBERT J (US); NELSON JAY C (US);  
WARREN LELAND (US)

Priority (No,Kind,Date): US 400515 A 19990920; US 170844 A3  
19981013; US 693398 A3 19960807; US 228809 B2 19940418

Applic (No,Kind,Date): US 400515 A 19990920

Addnl Info: 5955877 19990921 Patented; 5894218 19990413 Patented

National Class: \* 324758000; 324158100

IPC: \* B65G-049/07; G01R-031/26; H01L-021/66

Derwent WPI Acc No: \* G 95-373964; G 99-263246; G 99-539638; G  
01-089980; G 01-089980

Language of Document: English

Patent (No,Kind,Date): US 6210984 BA 20010403

METHOD AND APPARATUS FOR AUTOMATICALLY POSITIONING ELECTRONIC DIE  
WITHIN COMPONENT PACKAGES (English)

Patent Assignee: MICRON TECHNOLOGY INC (US)

Author (Inventor): FARNWORTH WARREN M (US); WOOD ALAN G (US);  
JACOBSON JOHN O (US); HEMBREE DAVID R (US); WARK JAMES M (US);  
FOLARON JENNIFER L (US); FOLARON ROBERT J (US); NELSON JAY C (US);  
WARREN LELAND (US)

Priority (No,Kind,Date): US 399640 A 19990920; US 170844 A3  
19981013; US 693398 A3 19960807; US 228809 B2 19940418

Applic (No,Kind,Date): US 399640 A 19990920

Addnl Info: 5955877 19990921 Patented; 5894218 19990413 Patented

National Class: \* 438015000; 438017000; 438010000; 438012000

IPC: \* H01L-021/66

Derwent WPI Acc No: \* G 95-373964; G 99-263246; G 99-539638; G  
01-089980

Language of Document: English

Patent (No,Kind,Date): US 6353312 BA 20020305

METHOD FOR POSITIONING A SEMICONDUCTOR DIE WITHIN A TEMPORARY PACKAGE  
(English)

Patent Assignee: MICRON TECHNOLOGY INC (US)

Author (Inventor): FARNWORTH WARREN M (US); FOLARON JENNIFER L (US);  
FOLARON ROBERT J (US); JACOBSON JOHN O (US); HEMBREE DAVID R (US);  
NELSON JAY C (US); WARREN LELAND (US)

Priority (No,Kind,Date): US 234226 A 19990120; US 767700 A3

19961217; US 228809 B1 19940418  
Applic (No,Kind,Date): US 234226 A 19990120  
Addnl Info: 6064194 Patented  
National Class: \* 324158100; 324765000; 324758000  
IPC: \* G01R-031/02  
Derwent WPI Acc No: \* G 95-373964; G 99-263246; G 99-539638; G  
01-089980  
Language of Document: English

UNITED STATES OF AMERICA (US)

Legal Status (No,Type,Date,Code,Text):

US 5894218	P	19940418	US AA	PRIORITY
			US 228809 B2 19940418	
US 5894218	P	19960807	US AE	APPLICATION DATA (PATENT)
			(APPL. DATA (PATENT))	
			US 693398 A 19960807	
US 5894218	P	19961007	US AS02	ASSIGNMENT OF ASSIGNOR'S
			INTEREST	
			MICRON TECHNOLOGY, INC. 8000 S. FEDERAL WAY	
			BOISE, IDAHO 83706-963 ; FOLARON, JENNIFER L.	
			: 19960927; FOLARON, ROBERT J. : 19960927;	
			NELSON, JAY C. : 19960927; WARREN, LELAN D. :	
			19960927	
US 5894218	P	19990413	US A	PATENT
US 5894218	P	19991116	US CC	CERTIFICATE OF CORRECTION
US 5955877	P	19940418	US AA	PRIORITY
			US 228809 B2 19940418	
US 5955877	P	19960807	US AA	PRIORITY
			US 693398 A3 19960807	
US 5955877	P	19981013	US AE	APPLICATION DATA (PATENT)
			(APPL. DATA (PATENT))	
			US 170844 A 19981013	
US 5955877	P	19990921	US A	PATENT
US 5955877	P	20010410	US CC	CERTIFICATE OF CORRECTION
US 6064194	P	19940418	US AA	PRIORITY
			US 228809 B1 19940418	
US 6064194	P	19961217	US AE	APPLICATION DATA (PATENT)
			(APPL. DATA (PATENT))	
			US 767700 A 19961217	
US 6064194	P	20000516	US A	PATENT
US 6064194	P	20011127	US CC	CERTIFICATE OF CORRECTION
US 6150828	P	19940418	US AA	PRIORITY
			US 228809 B2 19940418	
US 6150828	P	19960807	US AA	PRIORITY
			US 693398 A3 19960807	
US 6150828	P	19981013	US AA	PRIORITY
			US 170844 A3 19981013	
US 6150828	P	19990920	US AE	APPLICATION DATA (PATENT)
			(APPL. DATA (PATENT))	
			US 400515 A 19990920	
US 6150828	P	20001121	US A	PATENT
US 6210984	P	19940418	US AA	PRIORITY
			US 228809 B2 19940418	
US 6210984	P	19960807	US AA	PRIORITY (DIVISION)
			US 693398 A3 19960807	
US 6210984	P	19981013	US AA	PRIORITY (DIVISION)

US 170844 A3 19981013  
US 6210984 P 19990920 US AE APPLICATION DATA (PATENT)  
(APPL. DATA (PATENT))  
US 399640 A 19990920  
US 6210984 P 20010403 US BA PATENT (NO PREVIOUS  
PRE-GRANT PUBLICATION)  
US 6353312 P 19940418 US AA PRIORITY  
US 228809 B1 19940418  
US 6353312 P 19961217 US AA PRIORITY (DIVISION)  
US 767700 A3 19961217  
US 6353312 P 19990120 US AE APPLICATION DATA (PATENT)  
(APPL. DATA (PATENT))  
US 234226 A 19990120  
US 6353312 P 20020305 US BA PATENT (NO PREVIOUS  
PRE-GRANT PUBLICATION)